

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **08/26/2022**

Details for "TLV2374IPWG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV2374IPWG4	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	PW 14	4.4x5x1.15	67.4

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.069734	99.998566	999986	0.103467	1035
Precious Metals	Silver	7440-22-4	0.000001	0.001434	14	0.000001	0
Sub-Total			0.069735	100	1000000	0.103469	1035
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.348602	80.000092	800001	0.517235	5172
Thermoplastics	Epoxy	85954-11-6	0.08715	19.999908	199999	0.129308	1293
Sub-Total			0.435752	100	1000000	0.646543	6465
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	28.67088	97.52	975200	42.540178	425402
Copper and Its Alloys	Iron	7439-89-6	0.6762	2.3	23000	1.003306	10033
Copper and Its Alloys	Phosphorus	7723-14-0	0.00882	0.03	300	0.013087	131
Zinc and Its Alloys	Zinc	7440-66-6	0.0441	0.15	1500	0.065433	654
Sub-Total			29.4	100	1000000	43.622004	436220
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.113954	95.1202	951202	0.169078	1691
Precious Metals	Gold	7440-57-5	0.000934	0.779633	7796	0.001386	14
Precious Metals	Palladium	7440-05-3	0.004912	4.100167	41002	0.007288	73
Sub-Total			0.1198	100	1000000	0.177752	1778
Mold Compound							
Other Inorganic Materials	Silica	7631-86-9	30.555239	85	850000	45.33608	453361
Other Plastics and Rubber	Carbon Black	1333-86-4	0.179737	0.500001	5000	0.266683	2667
Thermoplastics	Epoxy	85954-11-6	5.212364	14.499999	145000	7.733801	77338
Sub-Total			35.94734	100	1000000	53.336565	533366
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.424552	100	1000000	2.113667	21137
Sub-Total			1.424552	100	1000000	2.113667	21137
Total			67.397179			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.